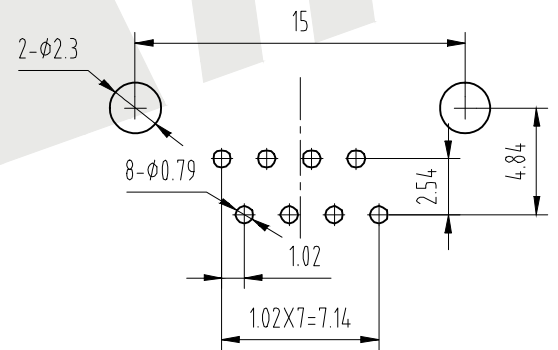
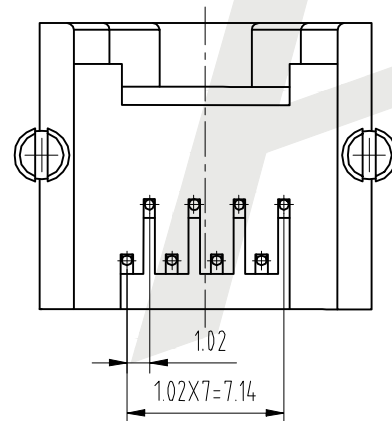
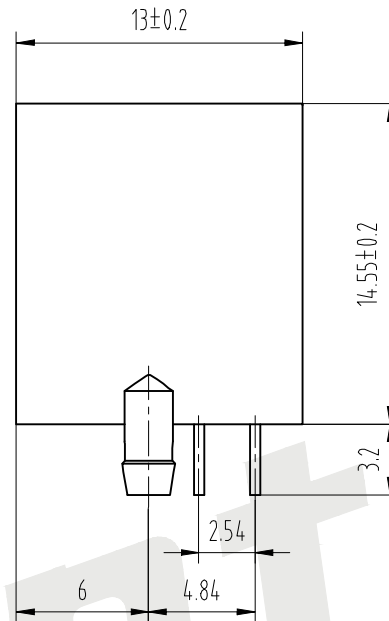
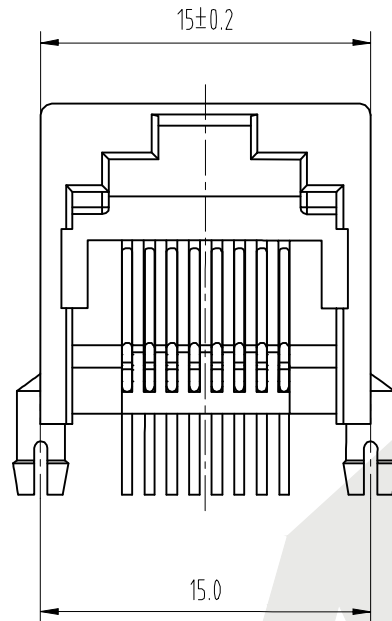


HSF



PC Board Layout
Component Side Shown

NOTES:

MATERIAL:

1. HOUSING MATERIAL: GLASS FILLED POYESTER UL94V-0.
2. CONTACT MATERIAL: PHOSPHOR BRONZE $t=0.3\text{mm}$
3. PLATING: SELECTING GOLD PLATING $1\mu \sim 50\mu$ OVER NICKEL IN CONTACT AREA. 150μ TIN PLATIN. OVER NICKEL IN SOLDER AREA
4. SHIELD: 0.2mm THICKNESS COPPER WITH NICKEL PLATE

ELECTRICAL

1. VOLTAGE RATING: 125VAC RMS
2. CURRENT RATING: 1.5AMP
3. CONTACT RESISTANCE: 30MILLIOHMS MAX
4. INSULATION RESISTANCE 500MEGOHMS MIN @500V DC
5. DIELECTRIC WITHSTANDING RESISTANCE : 1000V AC RMS 50Hz. 1MIN

MECHANICAL

1. DURRABILITY: 750 CYCLES MIN
2. PCB RETENTION PRB-SOLDER: 1 LB MIN

REVRONMENTAL

1. STORAGE: -40°C TO 85°C
2. OPERATION: 0°C TO 70°C

Order code:

ATRJ5521 - 8P - 8C - X - A - A
① ② ③ ④ ⑤ ⑥

- ① SERIES NO:
- ② NUMBER OF POSITIONS (8P, 6P, 4P)
- ③ NUMBER OF CONTACTS (8C, 6C, 4C)
- ④ Contact Plating
G0: Gold flash
G1: 3U" Gold
G2: 5U" Gold
G3: 10U" Gold
G4: 15U" Gold
G5: 30U" Gold
SN: Tin
- ⑤ Shield
A: W/O Shield
B: Half Shield
C: Shield W/Eml
D: Shield W/O Eml
- ⑥ Ports
A: 1X1P
B: 1X2P
C: 1X4P
D: 1X5P
E: 1X6P
F: 1X8P

Unless Otherwise specified tolerance
X. ± 0.35 X.XX: ± 0.20
X.X: ± 0.25 X.XXX: ± 0.15

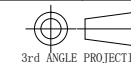
Antenk® ANTENK ELECTRONICS CO.,LTD
Http://www.antenk.com
E-mail:sales@antenk.com

SCALE: As Shown UNIT: mm
DRAW Wu Feng Rong DATE 06/09/2019
CHECK BobYang DATE 06/09/2019

TITLE: RJ11 Jack side entry, Full plastic

DRAWING NO: ATRJ5521-8P8C-X-A-A

PRODUCT NO: ATRJ5521-8P8C-X-A-A



REV	DESCRIPTION	DATE
1		
2		
3		
4		
5		